### Call for Book Chapters/Research Papers for Edited Book

To be published with ISBN under IIP International Publishers, USA & India

## **Futuristic Trends in Block Chain Applications**



**Series Editors** 



Dr. M. Sheik MuhideenBadhusha M.Sc., M.Phil.,Ph.D Dean of Research & Associate Professor Chemistry SadakathullahAppa College ( Autonomous)



P Mahamood Khan
Master of Engineering
Associate Professor
Electrical and Electronics Engineering
Vasireddy Venkatadri Institute of Technology
Andhra Pradesh, India.



Ph.D, M.Tech, B.E
Assistant Professor
Fashion Communication
National Institute Of Fashion Technology



Ph.D
Assistant Professor
SRM Arts And Science College
Kattankulathur, India

# Edited Book Series ID: IIPV3EBS19\_G2



**Iterative International Publishers** 

Novi, Michigan, USA Chikkamagaluru, Karnataka, India

#### **Imprint IIP**

Registered publisher under Raja Rammohun Roy Agency, Government of India and also under Bowker My Identifiers Agency, USA in the name of Selfypage Developers Pvt Ltd

**DOI Prefix: 10.58532** 

#### Important dates:

Paper submission portal opens from 12th June 2023 Last date for chapter submission: within 31st July 2023 Review status notification: within 31st July 2023 (Parallel Process)

Last date for resubmission/extended submission:  $28^{\text{th}}$  August 2023

Final Acceptance Notification: within 2<sup>nd</sup> September 2023 Last date for registration: within 14<sup>th</sup> October 2023

IIP Series www.iipseries.org



# Call for Chapters Futuristic Trends in Block Chain Applications

Book series ID: IIPV3EBS19\_G2 Submit chapter at: www.iipseries.org

Last date for chapter submission:28th August 2023

Publication month: December 2023

#### AIM & SCOPE

Among the scientific community, blockchain and AI are seen as a promising combination that will transform the production and manufacturing industry, media, finance, insurance, e-government, etc. Nevertheless, there is no consensus with schemes or best practices that would specify how blockchain and AI should be used together. Combining blockchain mechanisms and artificial intelligence is still a particularly challenging task. This book series is devoted to promoting the investigation of cutting-edge blockchain technology, to exploring the latest ideas, innovations, guidelines, theories, models, technologies, applications and tools of blockchain and AI for the industry, and to identifying critical issues and challenges that researchers and practitioners must deal with in future research. We want to offer researchers and practitioners the opportunity to publish their developments in this area.

#### Technologies and Techniques

1.Key and innovative theories, methodologies, schemes and technologies of blockchain and AI 2.Architectures and platforms for

- blockchain and AI
  3. Blockchain and AI for Big Data
- 4. Blockchain and AI for

Multi-Agent systems

- 5. Blockchain and AI for the Internet of Things
- 6. Blockchain and AI in 5G
- 7. Sensors and devices for blockchain 8. Distributed consensus mechanisms
- (PoW, PoS, PoE...)
  9. Encryption algorithms
- 10. Fault tolerance mechanisms
- 11. Other distributed ledger technologies
- 12. Cloud, fog, and edge computing approaches for blockchain
- 13. Blockchain standardization issues
- 14. Platforms for smart contracts
- 15. Side-chain and cross-chain systems
- 16. Anonymity and privacy in blockchain
- 17. Malicious transactions detection
- 18. 4th and 5th generation blockchain

#### Applications

- 1. Blockchain and AI enabled new business models and applications
- 2. Blockchain and AI for e-commerce
- 3. Blockchain and AI for logistics and transportation
- 4. Blockchain and AI for supply chain management
- 5. Blockchain and AI for product life cycle 6. Blockchain and AI for knowledge and innovation management
- 7. Blockchain and AI for agriculture
- 8. Blockchain and AI in eHealth
- 9. Applications of cryptocurrencies
- 10. Blockchain as a Tamper-Proof Technology
- 11. Application of smart contracts
- 12. Blockchain Governance and Human Rights
- 13. Applications of blockchain and AI in other domains.
- 14. Use-cases of blockchain and AI in Industry 4.0, banking, etc.
- 15. Blockchain and AI for fintech
- 16. Blockchain and AI for insurtech

#### **Author Benefits**

- 1. Peer reviewed publication
- 2. Selected chapters will be indexed in RSquareL and other indexing platforms including Amazon, Google Books etc.
- 3. Dual mode publication (One as an edited book with ISBN and another one as a Journal paper with ISSN)
- 4. DOI allotment to each chapter
- 5. Open access mode of publication in IIP Digital library
- 6. Optimised searching options to increase the visibility of the work to readers and other researchers which helps in citations
- 7. Unique dashboard to Author
- 8. Easy paper / chapter management system with transparency of the process including peer review
- 9. Adds points to API as per NAAC & NBA (India) and other accreditation bodies from abroad
- 10. One complimentary copy per chapter registration
- 11. Certificate to all authors who contributed chapter(s)

#### Chapter submission procedure:

- Step 1: Go to IIP website www.iipseries.org
- Step 2: Register in the portal by clicking on Signup
- Step 3: You can submit chapter at your dashboard or directly through IIP website after you login
- Step 4: Click on submit chapter for edited book
- Step 5: Select the book series title along with Book Series ID to which you wish to submit
- Step 6: Upload all necessary details along with your chapter in word file format. Refer **IIP Paper format** at download in IIP Website

#### Support from IIP to the Editors & Authors

- · Reviewing support from IIP Reviewers
- · Plagiarism checking service
- Submission management
- Registration management
- · Individual dashboard

For any queries
Contact: +91-8861512568
Mail us: info@iipseries.org

**Registration fee:** USD 30 INR.2000/- which includes processing fee with all above mentioned supporting services, Certificate hard copy to all authors, one complimentary copy of the book series per registration.

IIP Edited Book Series www.iipseries.org